Advantech Co., Ltd.
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RoHS Declaration of Conformity

Advantech pursues its social responsibility for global environmental preservation, hereby declaring that the product(s) listed in Annex 1 is in conformity with RoHS Directive (2011/65/EU and (EU) 2015/863) of the European Parliament on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

EU RoHS regulated Substances	Threshold *
Cadmium (Cd) / Cadmium Compounds	<100 ppm
Lead (Pb) / Lead Compounds	<1000 ppm
Mercury(Hg)/Mercury compounds	<1000 ppm
Hexavalent-Chromium (Cr^{6+}) Compounds	<1000 ppm
Polybrominated biphenyls(PBBs)	<1000 ppm
Polybrominated diphenyl ethers(PBDEs)	<1000 ppm
Bis (2-ethylhexyl) phthalate(DEHP)	<1000 ppm
Butyl benzyl phthalate (BBP)	<1000 ppm
Dibutyl phthalate(DBP)	<1000 ppm
Diisobutyl phthalate (DIBP)	<1000 ppm

*Threshold does not apply to applications covered by a RoHS substance exemption.

- The described product has been assessed and determined compliant with the relevant harmonized standard EN IEC 63000.

Annex 1

Part Numbers	Exemptions
ACP-2020G-85Z	6(c);7(a);7(c)-I

YS Yang

Ys.Yang
Associate Vice President
Date: 2023/8/18

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RoHS Exemption Reference
6(a)-I. Lead as an alloying element in steel for machining purposes containing up to 0.35 percent lead by weight and in batch hot dip galvanized steel components containing up to 0.2 percent lead by weight
6(b)-I. Lead as an alloying element in aluminium containing up to 0,4 % lead by weight, provided it stems from lead-bearing aluminium scrap recycling
6(b)-II. Lead as an alloying element in aluminium for machining purposes with a lead content up to 0,4 % by weight
6(c). Copper alloy containing up to 4% lead by weight.
7(a). Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
7(c)-I. Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.
7(c)-II. Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher.
8(b)-I. Cadmium and its compounds in electrical contacts used in *- circuit breakers;* *- thermal sensing controls;* *- thermal motor protectors (excluding hermetic thermal motor protectors* *- AC switches rated at 6 A and more at 250 V AC and more, or 12 A and more at 125 V AC and more* *- DC switches rated at 20 A and more at 18 V DC and more, and* *- Switches for use at voltage supply frequency ≥ 200 Hz*
15(a). Lead (Pb) in solders to complete a viable electrical connection between the semiconductor die and carrier within integrated circuit flip chip packages where at least one of the following criteria applies: *- a semiconductor technology node of 90 nm or larger;* *- a single die of 300 mm2 or larger in any semiconductor technology node;* *- stacked die packages with die of 300 mm2 or larger, or silicon interposers of 300 mm2 or larger.*